ABSTRACT

A method for fabricating an anisotropic conductive substrate is disclosed. A back holder has metal pins on a surface thereof. A liquid compound is formed on the surface of the back holder with metal pins. The liquid compound is pressed to deform the metal pins into electrodes in the liquid compound. The thickness between upper surface and lower surface of the liquid compound is between 25 μm and 250 μm. The electrodes have upper ends and lower ends exposed from upper surface and lower surface of the liquid compound to provide electrical contact of anisotropic conduction.